

## N-Channel Super Junction Power MOSFET IV

### General Description

The series of devices use advanced trench gate super junction technology and design to provide ultra-low  $R_{DS(ON)}$  and low gate charge and With a rapid recovery body diode. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, industrial power applications, Fast charger, new energy vehicle charging pile, on-board OBC etc.

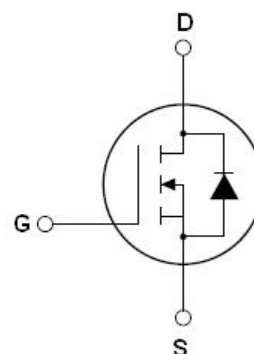
### Features

- New technology for high voltage device
- Ultra low on-resistance and ultra low conduction losses
- Ultra Low Gate Charge cause lower driving requirements
- Diode reverse recovery speed is super fast
- High reliability
- ROHS compliant

### Application

- Power factor correction (PFC)
- Switched mode power supplies (SMPS)
- Uninterruptible Power Supply (UPS)
- On-board charger (OBC)

$V_{DS\ min@T_{jmax}}$	710	V
$R_{DS(ON)TYP}$	85	mΩ
$I_D$	36	A
$Q_g$	55	nC



Schematic diagram

✧ Intrinsic fast-recovery body diode

### Package Marking And Ordering Information

Device	Device Package	Marking
NCE65NF099F	T0-220F	NCE65NF099F



Table 1. Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ )

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS}=0V$ )	$V_{DS}$	650	V
Gate-Source Voltage ( $V_{DS}=0V$ ) AC ( $f>1\text{ Hz}$ )	$V_{GS}$	$\pm 30$	V
Gate-Source Voltage ( $V_{DS}=0V$ ) DC	$V_{GS}$	$\pm 20$	V
Continuous Drain Current at $T_c=25^\circ\text{C}$	$I_D (DC)$	36	A
Continuous Drain Current at $T_c=100^\circ\text{C}$	$I_D (DC)$	25.2	A
Pulsed drain current (Note 1)	$I_{DM (pluse)}$	108	A
Maximum Power Dissipation ( $T_c=25^\circ\text{C}$ )	$P_D$	35	W
Derate above $25^\circ\text{C}$		0.23	W/ $^\circ\text{C}$
Single pulse avalanche energy (Note 2)	$E_{AS}$	324	mJ
Avalanche current (Note 1)	$I_{AS}$	9	A
Repetitive Avalanche energy, $t_{AR}$ limited by $T_{jmax}$ (Note 1)	$E_{AR}$	0.39	mJ

Parameter	Symbol	Value	Unit
Drain Source voltage slope, $V_{DS} \leq 480V$ ,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \leq 480V, I_{SD} < I_D$	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55...+175	°C

\* limited by maximum junction temperature

**Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	$R_{thJC}$	4.29	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	$R_{thJA}$	62	°C /W

**Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =1mA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			400	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =500uA	3	4	5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =18A		85	99	mΩ
Dynamic Characteristics						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V, F=1.0MHz		2800	3200	pF
Output Capacitance	C <sub>oss</sub>			96		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			6		pF
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =480V,I <sub>D</sub> =18A, V <sub>GS</sub> =10V		55	60	nC
Gate-Source Charge	Q <sub>gs</sub>			16.5		nC
Gate-Drain Charge	Q <sub>gd</sub>			25.5		nC
Gate plateau voltage	V <sub>gp</sub>			7.3		V
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		1.5		Ω
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =380V,I <sub>D</sub> =18A, R <sub>G</sub> =1.7Ω,V <sub>GS</sub> =10V		15		nS
Turn-on Rise Time	t <sub>r</sub>			14		nS
Turn-Off Delay Time	t <sub>d(off)</sub>			72		nS
Turn-Off Fall Time	t <sub>f</sub>			14		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T <sub>C</sub> =25℃			36	A
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>				108	A
Forward On Voltage	V <sub>SD</sub>	T <sub>J</sub> =25℃,I <sub>SD</sub> =36A,V <sub>GS</sub> =0V		1.0	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> =25℃,I <sub>F</sub> =18A,di/dt=100A/μs		160		nS
Reverse Recovery Charge	Q <sub>rr</sub>			0.96		uC
Peak Reverse Recovery Current	I <sub>rrm</sub>			12		A

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2.  $T_J=25^\circ C, V_{DD}=50V, V_G=10V, R_G=25\Omega$

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

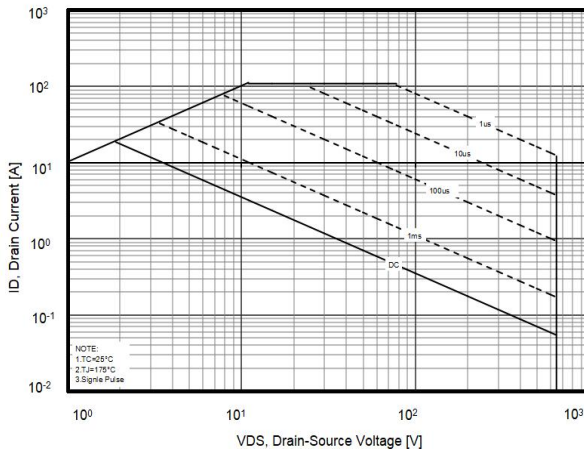


Figure2. Capacitance

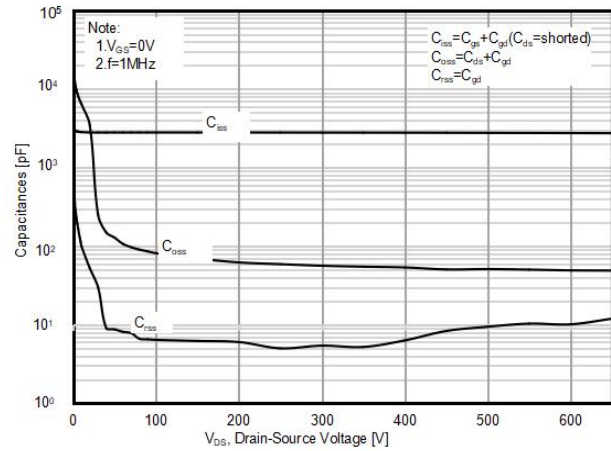


Figure3. Output characteristics

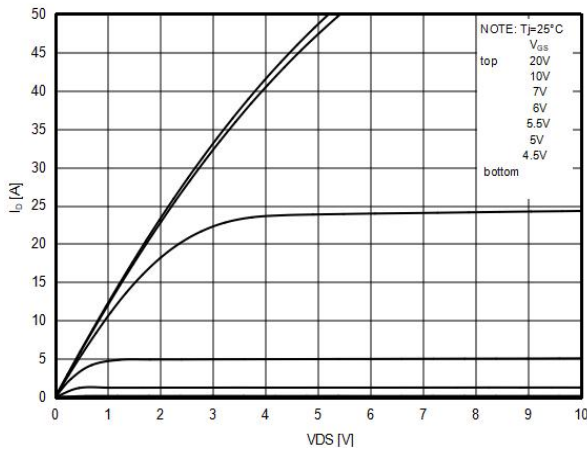


Figure4. Source-Drain Diode Forward Voltage

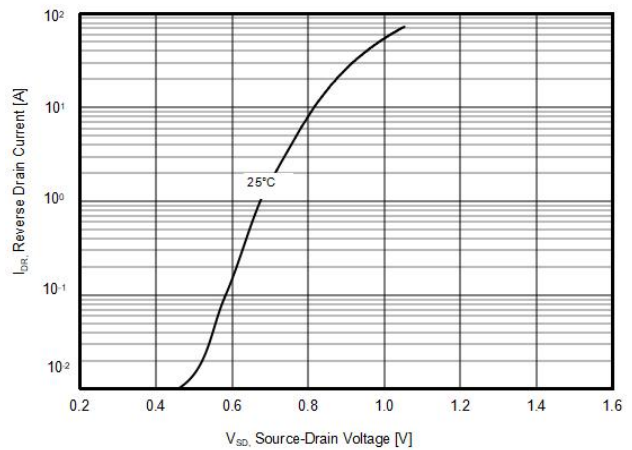


Figure5. Static drain-source on resistance

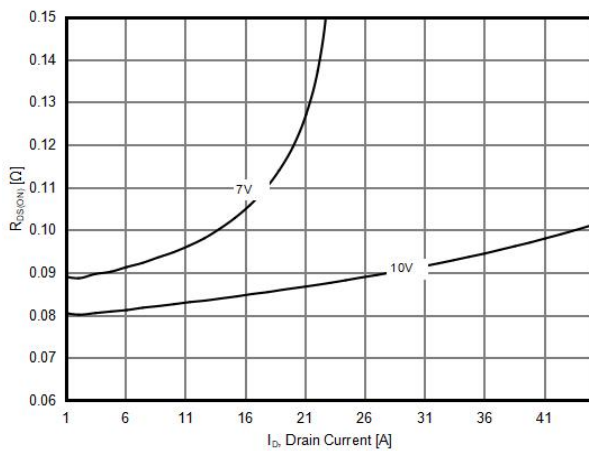
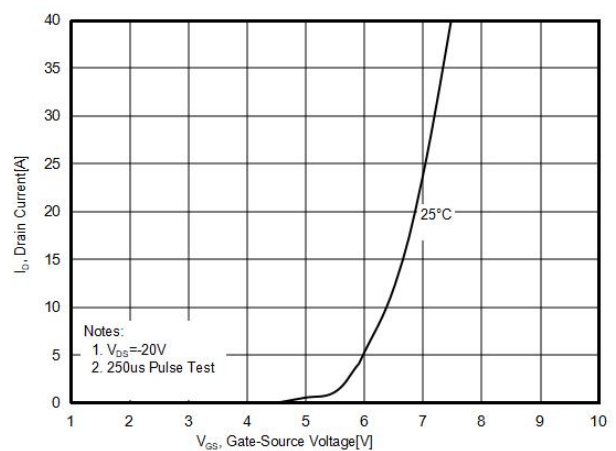
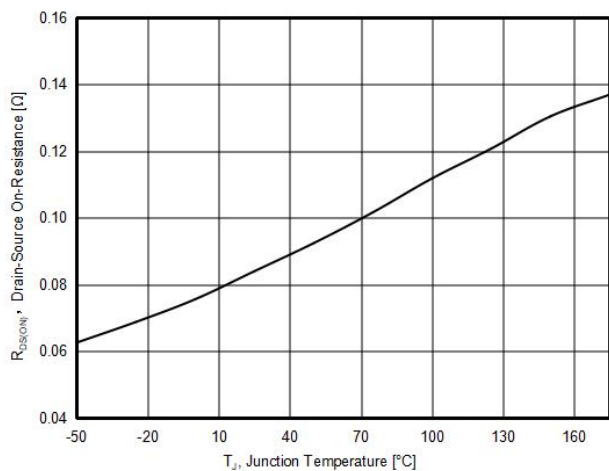


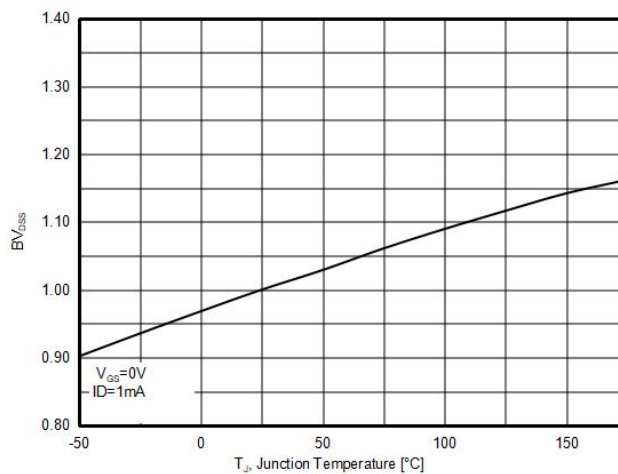
Figure6. Transfer characteristics



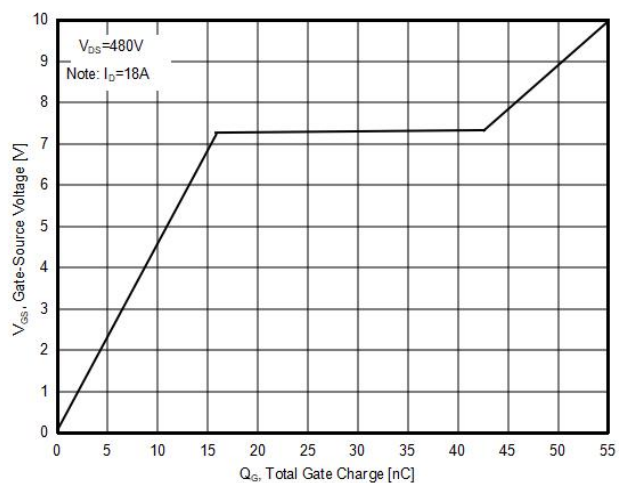
**Figure7.  $R_{DS(ON)}$  vs Junction Temperature**



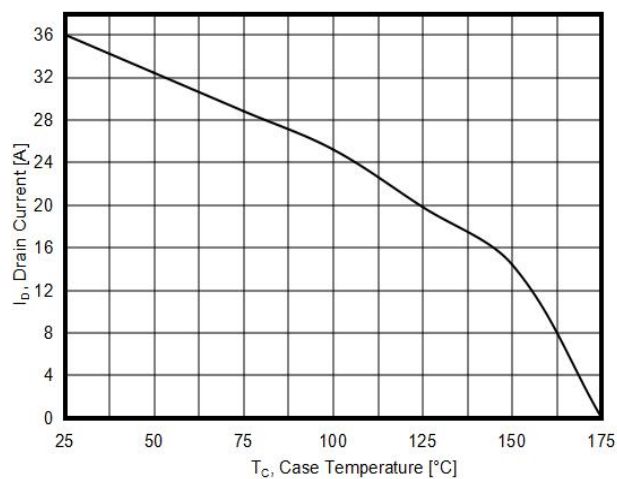
**Figure8.  $BV_{DSS}$  vs Junction Temperature**



**Figure9. Gate charge waveforms**



**Figure10. Maximum  $I_D$  vs Junction Temperature**



## Test circuit

### 1) Gate charge test circuit & Waveform



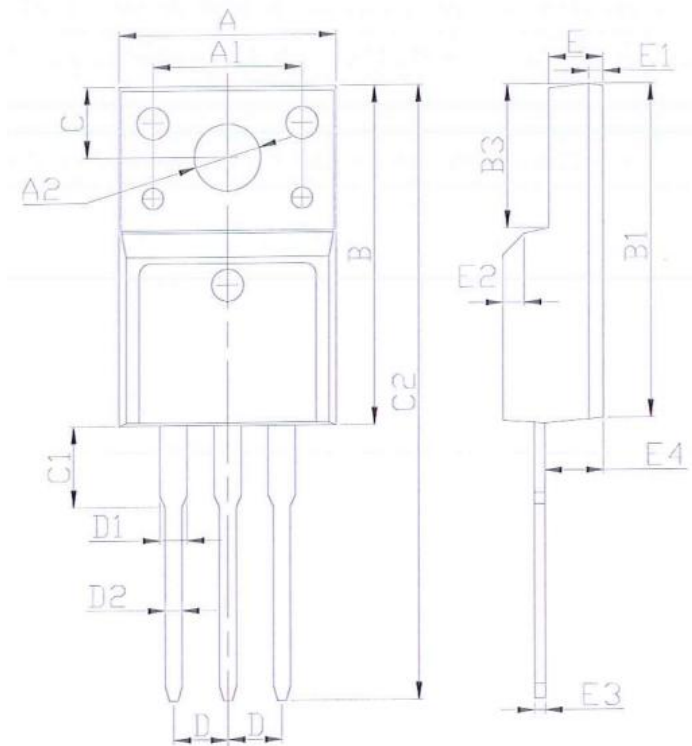
### 2) Switch Time Test Circuit:



### 3) Unclamped Inductive Switching Test Circuit & Waveforms



## TO-220F-L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	9.86	10.46	0.387	0.411
A1	6.80	7.20	0.267	0.283
A2	2.92	3.32	0.115	0.130
A3	9.40	10.00	0.369	0.393
B	15.40	16.40	0.605	0.644
B1	15.10	16.10	0.593	0.633
B2	4.40	5.00	0.173	0.196
B3	6.40	7.00	0.251	0.275
C	3.05	3.55	0.120	0.139
C1	2.95	3.55	0.116	0.139
C2	28.20	29.20	1.108	1.147
D	2.54 BSC		0.100 BSC	
D1	--	1.47	--	0.058
D2	0.60	1.00	0.024	0.039
E	2.30	2.80	0.090	0.110
E1	0.45	0.95	0.018	0.037
E2	45.0°		45.00°	
E3	0.30	0.70	0.012	0.028
E4	2.45	3.05	0.096	0.120

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